



THERMAL CONDUCTIVE ADHESIVE TAPE – TH-10NF

The TH-10NF Thermally conductive adhesive tape possesses extremely high thermal conductivity of 2.5w/mk and low thermal impedance, yet still maintains a high binding strength.

The tape can be used to replace thermal filler pads and thermal grease with mechanical fixings. Applications include bonding Heat Sinks, Microprocessors and LEDs.

Features

- Thermal Conductivity 2.5 W/m-k
- High bond strength to a variety of surfaces.
- Double sided pressure sensitive adhesive tape.
- High performance thermally conductive acrylic adhesive.

Application

- Mounting heatsinks on BGA processor or drive processor.
- Mounting heat spreader onto PCB or onto motor control PCB.
- Can be used instead of heat cure adhesive, screw mounting or clip mounting.

Item	TH-10NF	Test Method
Sheet size (mm)	300x300	-
Adhesive Type	Acrylic Adhesive	-
Continuous Use Temp.	-40 ~ 120(°C)	-
Thickness	0.15mm	ASTM D374
Thickness Tolerance	0.02	ASTM D374
Voltage Breakdown	>3000 Vac	ASTM D149
Steel adhesion (g/25mm)	800	ASTM E 1000
Thermal Impedance @50psi	0.31	-
Thermal Conductivity	2.5 w/mk	ASTM D5470
Volume Resistivity (Ω-cm)	10 ¹⁴	ASTM D 257
Hardness (Shore A)	33+/-5	JIS K 6301A
Holding Power (25°C/Hours)	> 48 Hours	PSTC-7
Holding Power (80°C/Hours)	> 48 Hours	PSTC-7

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